

Copper Etching

SODIUM CHLORATE SOLUTION, 39% Liquid solution for etch generation.

SODIUM CHLORATE SOLUTION, 46% Economical liquid solution for etch generation.

Tin/Solder Stripping

Single Step

NPS 3002 Extremely fast, non-sludging, nitric based tin/solder stripper for spray applications. Provides a maximum possible loading of up to a SG of 1.36. Low copper etch rate results in a bright copper finish.

NPS 3000 Nitric based tin/solder stripper for spray applications.

SELECT STRIP PLUS Peroxide/bifluoride solder stripper. Excellent for selective tin or tab stripping.

Two Step

NPS 10 & NPS 20 High capacity and low exotherm. Leaves a bright copper finish.

MAGNUM NPS 220 & NPS 240 Economical tin/solder remover.

HAL/Fusing

HAL Fluxes

FLO RITE LV Low viscosity flux ideal for fine pitch surface mounts.

FLO RITE 150 Low viscosity hot air leveling flux.

FLO RITE 300 Medium viscosity hot air leveling flux.

LEVELCOTE 250 Low viscosity, horizontal hot air leveling flux.

LEVELCOTE COVER OIL 200 For use in conjunction with Levelcote Flux 250.

Post Cleaning

RINSE AIDE 90 Highly concentrated flux residue remover for either spray or soak applications.

QUENCH AIDE 96 Reduces temperatures of panels at a steady rate after hot air leveling or fusing to reduce thermal stress.

Hot Oil Fusing

THERMO FLO® High performance, long lasting formula with exceptional fusing characteristics.

291 FLUX Non-flammable, mildly active formula.

Film Cleaning

SPECIAL FILM CLEANER Excellent hexane free antistatic cleaner for diazo, silver halide and protective films. Available in unscented version.

Equipment Cleaning

TIDY SUMP General purpose, alkaline equipment cleaner for developers and resist strippers.

CITRISUMP Organic acid formula exceptional at removing solder mask, carbonate residues and hard water scale.

TIDYLINE EQ-100 Concentrated alkaline equipment cleaner. Excellent at removing stains.

SUMP DOCTOR Alkaline equipment cleaner designed to break antifoam residues.

Soldermask Stripping

MAGNASTRIP 500 High speed, long lasting soldermask remover. No scrubbing required and no attack on the laminate.

MAGNASTRIP 600HF Specifically designed to remove most liquid photoimageable solder masks from halogen free laminates quickly and without damaging the surface of the laminate or causing measling

Screen Cleaning

EV SCREEN CLEANER Wipe off screen cleaner that rapidly removes inks from screens and boards without leaving a residue.

DPC-20 Fast acting, safe solvent based material for the removal of uncured printing inks, soldermasks and tape residues. Does not contain any chlorinated hydrocarbons or flammable solvents.

SCREENSOL SC-55 Screen wash for removing uncured resist and inks on screen mesh without damaging the emulsion or image.

SCREENSOL ER-200 Concentrated emulsion/stencil remover for screens. Leaves no residue.



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Developing

DX-32 Economical, easy to use, one part carbonate based liquid developer concentrate for fully or semi-aqueous dry films and LPI solder masks. Stabilizers increase solution pH to produce 15 to 20% more throughput.

DX-40 40% potassium carbonate with additives for improved sidewalls. Produces higher yields and faster speeds.

DX-45 45% potassium carbonate. Replenishing solution for DX-40 and ADC-40.

ADC-40 40% potassium carbonate. Economical electronic-grade concentrate.

DR-503 CX 38% potassium carbonate. Contains additives for higher loading. Designed to be used for single solution make-up and replenishment.

Antifoams

ANTIFOAM BB Highly concentrated formula for use with photoresist strippers, photoresist developers and LPI developers.

ANTIFOAM DES Concentrated water-miscible antifoam for use in developers and resist strippers. Highly effective in both alkaline and acid solutions.

Resist Stripping

Innerlayer

DUAL STRIP BAT Highly effective stripper for any liquid or dry film inner layer resist. Strong anti-tarnish package to maximize productivity at AOI.

ULTRA STRIP BAT General purpose inner layer stripper. Low pH working solution. Excellent with flex.

ADF-55 Quickly removes both dry film and liquid resist in soak or spray applications. Compatible with most oxide alternative pre-clean cycles. Produces filterable particles with low VOC content.

Outerlayer

MICROSTRIP 2000 High speed stripper designed to remove the toughest adhering resists by creating very small particles. Ideal for overplate conditions.

ADF-25C A fully aqueous, highly concentrated stripper producing high speeds and small particles. Ideal for fine lines and spaces.

Dual Purpose

ADF-30 Strong, consistent performance on a wide variety of photoresists. Fast strip speeds producing filterable particles.

ADF-14 BAT General purpose resist stripper for a broad range of photoresists.

Flex

FLEXSTRIP Low pH stripper designed for stripping dry film resists from adhesive-less and adhesive-based flex laminates.

Copper Cleaning

Innerlayer

LAYERCLEAN CR Highly concentrated, chloride-free, non-etching copper cleaner for fast removal of chromate conversion coatings from standard and reverse-treat foils.

ULTRACLEAN NF General purpose alkaline cleaner for removal of organics and fingerprints from copper surfaces.

Pre-Plate

POSICLEAN[®]C Non-etching, phosphoric based pattern plate cleaner for immersion applications. Consistently provides extended bath life and removes all organic and inorganic soils prior to acid copper plating.

POSICLEAN[®]B Hydrochloric based pattern plate cleaner for immersion applications. Provides complete cleaning of organic and inorganic soils without excess copper attack.

POSICLEAN[®]M Sulfuric based pattern plate cleaner for immersion applications. Removes oxidation, tarnish and organic soils prior to pattern plating.

AT-3000 Concentrated acid based anti-tarnish for use after electroless copper or any other process that requires an extended hold time or adhesion promoter.

Microetch

ME-515 Potassium monopersulfate microetch, producing a uniform predictable etch rate with maximum surface topography. Remains very stable in solution over long periods.

ME-515L Liquid sodium persulfate microetch designed for spray applications.

QUANTUM ETCH Stabilized peroxide based microetch for spray or immersion applications.

SUR CLEAN 92 Ferric chloride based acid copper cleaner or microetch for general purpose applications.

ACCUCLEAN NF Mild low etching, non-foaming, hydrochloric based cleaner designed for spray applications.

Desmear & Electroless Copper

Desmear/Etchback

MAGNUM S-400 Biodegradable, highly effective sensitizer for use prior to permanganate. Ideal for either desmear or etchback applications.

MAGNUM K-401 Low cost potassium permanganate designed for desmear applications of conventional resins. Maximizes surface topography for superior adhesion of electroless copper.

MAGNUM N-501 Concentrated sodium permanganate designed for desmear and etchback applications on high T_g resins. Provides maximum surface topography for superior adhesion of electroless copper.

MAGNUM N-599 Neutralizer for permanganate residues.

MAGNUM GE-600 A non-ammoniated glass etch for use in either desmear or etchback applications.

Pre-Plate

CIRCUTEK CC-710 Alkaline cleaner/conditioner designed to clean and condition the glass and resin for better electroless copper coverage.

CIRCUTEK PD-776 Liquid pre-dip to neutralize the substrate and prevent water drag-in into the activator.

CIRCUTEK PD-776 S Powdered version of the PD-776.

CIRCUTEK C-777 Colloidal palladium activator to catalyze substrates for subsequent electroless copper plating.

CIRCUTEK A-778 Accelerator for modifying the activated surface to improve hole wall adhesion.

Electroless Coppers

CIRCUTEK PC-701 Highly stable, quadrol based electroless copper designed to deposit 70-90 microinches in 30 minutes at 90-110°F. Produces a uniform copper deposit with excellent resistance to subsequent processes.

CIRCUTEK EC-1050 Highly stable, quadrol based thin deposition electroless copper designed to plate 25-50 microinches in 15-30 minutes at 75-90°F.

Electrolytic Plating

CU BRITE PC-525 One part additive for bright acid copper plating. Resulting deposit provides superior thermal stress performance.